507684266 01/09/2023

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

SUBMISSION TYPE: CORRECTIVE ASSIGNMENT **NATURE OF CONVEYANCE:** Corrective Assignment to correct the CONVEYING PARTY previously recorded on Reel 053339 Frame 0149. Assignor(s) hereby confirms the ASSIGNMENT.

CONVEYING PARTY DATA

| Name | Execution Date |
|---------------|----------------|
| LIN ZHANG | 01/08/2020 |
| HUO YUN DUAN | 01/08/2020 |
| XI LIN LI | 01/08/2020 |
| CHEN XIONG | 01/08/2020 |
| XIAO LIN KANG | 01/08/2020 |

RECEIVING PARTY DATA

| Name: | TEXAS INSTRUMENTS INCORPORATED |
|-----------------|--------------------------------|
| Street Address: | 12500 TI BOULVEARD |
| City: | DALLAS |
| State/Country: | TEXAS |
| Postal Code: | 75243 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 16941701 |

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-479-1232 Email: uspto@ti.com

TEXAS INSTRUMENTS INCORPORATED **Correspondent Name:**

Address Line 1: P O BOX 655474, MS 3999 Address Line 4: DALLAS, TEXAS 75265

ATTORNEY DOCKET NUMBER: T91001US01 NAME OF SUBMITTER: RICHANDA DAVIS SIGNATURE: /Richanda Davis/ **DATE SIGNED:** 01/09/2023

Total Attachments: 4

PATENT REEL: 062325 FRAME: 0818

EPAS ID: PAT7731408

507684266

source=T91001US01_Cover_Sheet#page1.tif source=T91001US01_ExecutedAssignment#page1.tif source=T91001US01_ExecutedAssignment#page2.tif source=T91001US01_ExecutedAssignment#page3.tif

> PATENT REEL: 062325 FRAME: 0819

506176803 07/29/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

yleeneet vereien viiz

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|--------------|----------------|
| LIN ZHANG | 01/08/2020 |
| HUO YUN DUAN | 01/08/2020 |
| XI LIN LI | 01/08/2020 |
| CHEN XIONG | 01/08/2020 |

RECEIVING PARTY DATA

| Name: | TEXAS INSTRUMENTS INCORPORATED |
|-------------------|--------------------------------|
| Street Address: | 12500 TI BOULEVARD |
| Internal Address: | MS 3999 |
| City: | DALLAS |
| State/Country: | TEXAS |
| Postal Code: | 75243 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 16941701 |

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-479-1230 **Email:** uspto@ti.com

Correspondent Name: TEXAS INSTRUMENTS INCORPORATED

Address Line 1:P O BOX 655474, MS 3999Address Line 4:DALLAS, TEXAS 75265

| ATTORNEY DOCKET NUMBER: | TI-91001 |
|-------------------------|------------------|
| NAME OF SUBMITTER: | JACKIE MCBRIDE |
| SIGNATURE: | /Jackie McBride/ |
| DATE SIGNED: | 07/29/2020 |

Total Attachments: 3

source=TI-91001_ExecutedAssignment#page1.tif

PATENT REEL: 062325 FRAME: 0820

EPAS ID: PAT6223541

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

| TITLE | COPPER WIRE BOND ON GOLD BUMP ON SEMICONDUCTOR DIE BOND PAD | | |
|-----------------------------------|---|-------------|---------------|
| NONPROVISIONAL APPLICATION NO. | 16/941,701 | FILING DATE | July 29, 2020 |

| SIGNATURE OF INVENTOR | 张林 |
|---------------------------------|------------------------------|
| PRINTED NAME OF INVENTOR | Lin Zhang |
| DATE | 7020.1.8 |
| RESIDENCE (CITY and COUNTRY) | Chengdu City, Sichuan, China |

PATENT REEL: 062325 FRAME: 0821

Application No.

Attorney Docket No. TI-91001

| SIGNATURE OF INVENTOR | 英·K·文 |
|---------------------------------|------------------------------|
| PRINTED NAME OF INVENTOR | Huo Yun Duan |
| DATE | 200-1.8 |
| RESIDENCE (CITY AND COUNTRY) | Chengdu City, Sichuan, China |

| SIGNATURE OF INVENTOR | 李春林 |
|---------------------------------|-------------------------|
| PRINTED NAME OF INVENTOR | Xi Lin Li |
| DATE | 2020.1.8 |
| RESIDENCE (CITY AND COUNTRY) | Chengdu, Sichuan, China |

| SIGNATURE OF INVENTOR | 4 |
|---------------------------------|-------------------------|
| PRINTED NAME OF INVENTOR | Chen Xiong |
| DATE | 20 N. 1. 8 |
| RESIDENCE (CITY AND COUNTRY) | Chengdu, Sichuan, China |

PATENT REEL: 062325 FRAME: 0822

Application No.

Attorney Docket No. TI-91001

| SIGNATURE OF INVENTOR | 美子科 |
|---------------------------------|-------------------------|
| PRINTED NAME OF INVENTOR | Xiao Lin Kang |
| DATE | 2020, 1, 8 |
| RESIDENCE (CITY AND COUNTRY) | Chengdu, Sichuan, China |

PATENT REEL: 062325 FRAME: 0823

RECORDED: 01/09/2023